Final Finishing – ENEPIG Technology
表面處理 – 化学镍钯金技術

PALLAMERSE™ SMT2000 Electroless Palladium

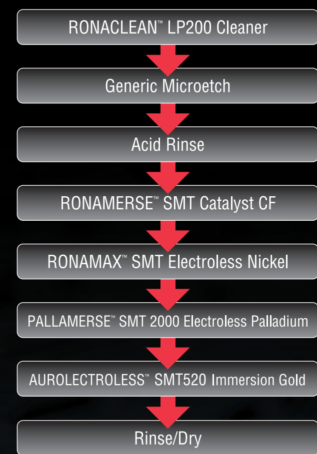
The Palladium layer protects the Nickel layer from corrosion and inhibits the phosphorous rich layer growth to provide outstanding reliability.

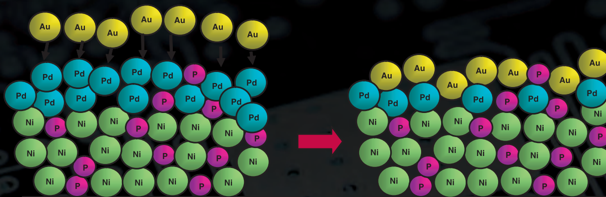
钯层保护镍层并抑制富磷层增生，表现出优异的焊点可靠度。

Advantages 优点

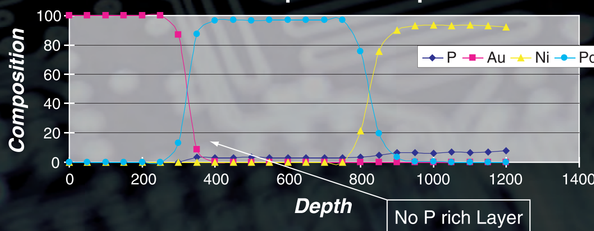
- Electroless palladium layer prevents attack of Cu/Ni substrate
  化学钯层防止铜与镍层被攻击
- Excellent wire bondability with thin gold deposit
  配合薄金镀层表现出优越之打金线接合能力
- Well buffered system and easy maintenance procedure for bath solution
  优异及简易的槽液控制系统
- Excellent selectivity of deposition eliminate outer growth problem
  高度选择性沉积
- Outstanding Pd/Au plating on both copper and nickel
  在铜及镍层有优异的钯金沉积能力

ENEPIG Process 流程





Ni/Pd/Au Depth vs. Composition



	Nickel Outer Growth Issue	Fine Line Design	Ball Bonding Ability	Wire Bonding Ability	Cost	Bath Stability
PALLAMERSE EL-Ni/EL-Pd/IM-Au	**O**	**O**	**O**	**O**	**O**	**O**
ENIG EL-Ni/iM-Au(Thin)	△ Boundary Corrosion	O	O	X	O	O
ENIG EL-Ni/iM-Au(Thick)	△ Boundary Corrosion	O	O	O	X	△
Direct Au	O	O	O	O	X	X
Electro Ni/ Electro Au	O	X	O	O	X	O

Electronic Materials

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